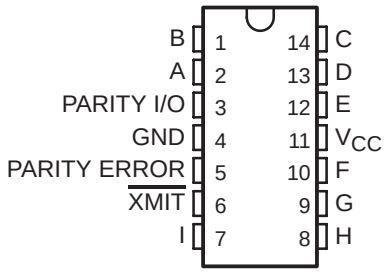
- **Inputs Are TTL-Voltage Compatible**
- **Generates Either Odd or Even Parity for Nine Data Lines**
- **Cascadable for n-Bits Parity**
- **Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic 300-mil DIPs (N)**

D OR N PACKAGE
(TOP VIEW)



description

The 74ACT11286 universal 9-bit parity generator/checker features a local output for parity checking and a bus-driving parity I/O port for parity generation/checking. The word-length capability is easily expanded by cascading.

The $\overline{\text{XMIT}}$ control input is implemented specifically to accommodate cascading. When the $\overline{\text{XMIT}}$ is low, the parity tree is disabled and the PARITY ERROR output remains at a high logic level, regardless of the input levels. When $\overline{\text{XMIT}}$ is high, the parity tree is enabled. PARITY ERROR indicates a parity error when either an even number of inputs (A through I) are high and PARITY I/O is forced to a low logic level, or when an odd number of inputs are high and PARITY I/O is forced to a high logic level.

The I/O control circuitry is designed so that the I/O port remains in the high-impedance state during power up or power down, to prevent bus glitches.

The 74ACT11286 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE

NUMBER OF INPUTS (A−I) THAT ARE HIGH	$\overline{\text{XMIT}}$ INPUT	PARITY I/O	PARITY ERROR OUTPUT
0, 2, 4, 6, 8	l	H	H
1, 3, 5, 7, 9	l	L	H
0, 2, 4, 6, 8	h	h	H
	h	l	L
1, 3, 5, 7, 9	h	h	L
	h	l	H

h = high input level, H = high output level, l = low input level, L = low output level

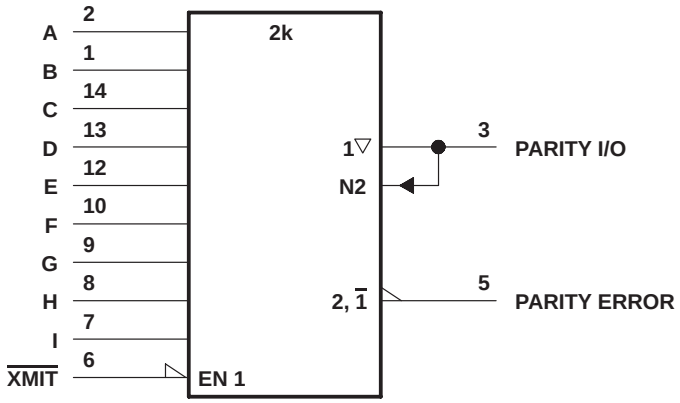
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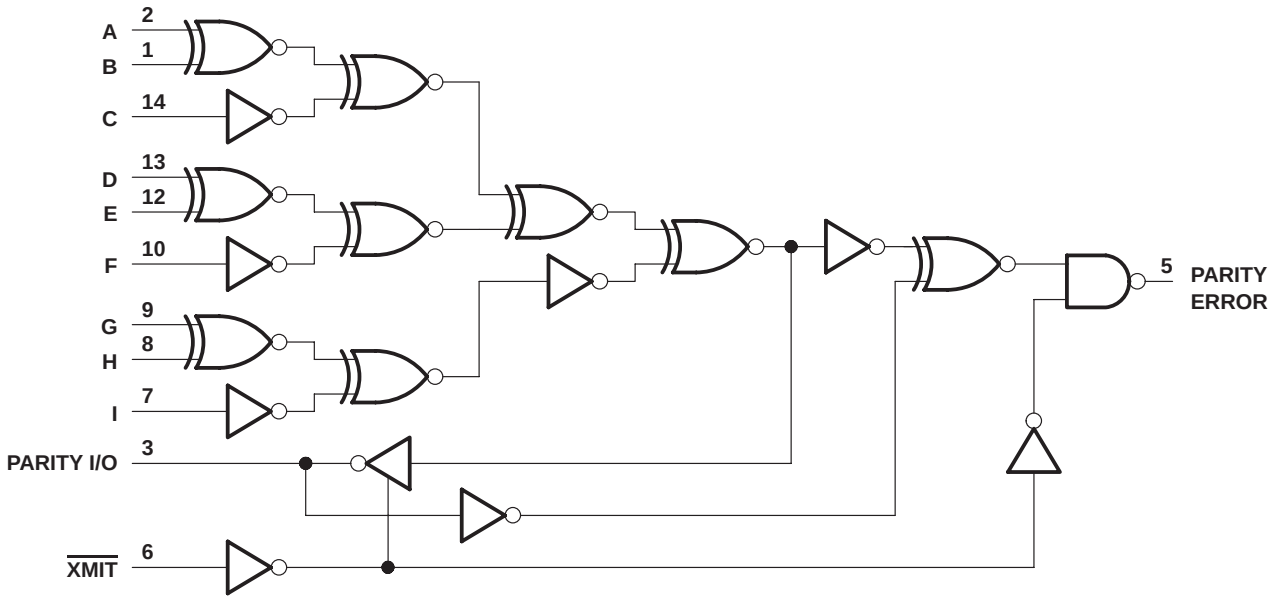
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) . . . . . ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±100 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package . . . . . 1.25 W
N package . . . . . 1.1 W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions

		MIN	MAX	UNIT
V_{CC}	Supply voltage	4.5	5.5	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current		−24	mA
I_{OL}	Low-level output current		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
T_A	Operating free-air temperature	−40	85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = −50 μA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = −24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}		I_L = 50 μA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_{OZ}	PARITY I/O	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
I_I	Except PARITY I/O	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}‡		One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.9		1	mA
C_i		$V_I = V_{CC}$ or GND	5 V		3.5				pF
C_o	PARITY I/O	$V_O = V_{CC}$ or GND	5 V		8				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V to V_{CC}.

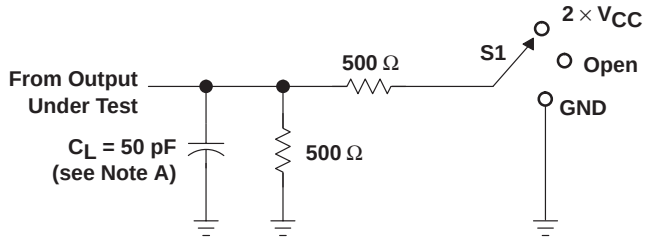
switching characteristics over recomended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	Any A−I	PARITY I/O	2.7	6.1	9	2.7	10.4	ns
t_{PHL}			3.6	7.3	10.8	3.6	12	
t_{PLH}	Any A−I	PARITY ERROR	3	6.9	9.7	3	11.3	ns
t_{PHL}			3.9	7.7	11.4	3.9	12.9	
t_{PLH}	PARITY I/O	PARITY ERROR	2.2	4.6	6.8	2.2	7.7	ns
t_{PHL}			3.1	5.6	8.3	3.1	9.1	
t_{PZH}	$\overline{XMIT}$	PARITY I/O	1.8	4.2	6.3	1.8	7.3	ns
t_{PZL}			3	6.3	9.4	3	11.4	
t_{PHZ}	$\overline{XMIT}$	PARITY I/O	4.7	6.5	7.9	4.7	8.5	ns
t_{PLZ}			4.1	6	7.3	4.1	7.8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

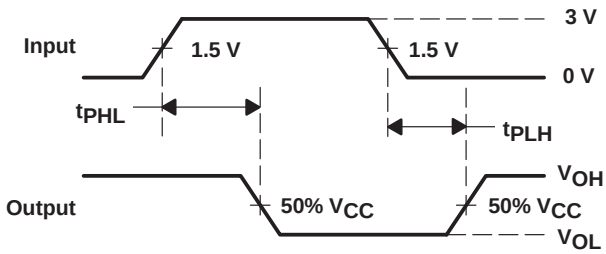
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 1 MHz	56	pF
		Outputs disabled		50	

PARAMETER MEASUREMENT INFORMATION

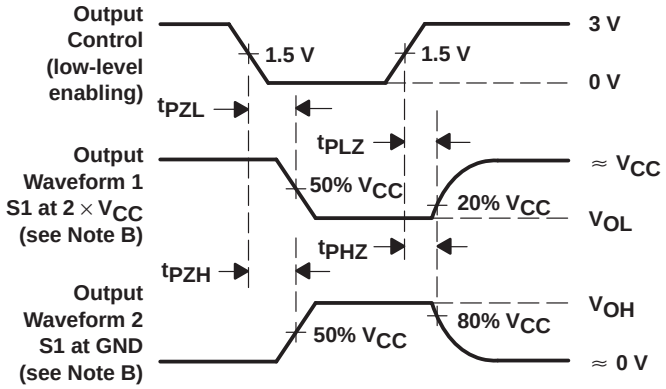


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74ACT11286D	Last Time Buy	Production	SOIC (D) | 14	50 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT11286
74ACT11286D.A	Last Time Buy	Production	SOIC (D) | 14	50 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT11286

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

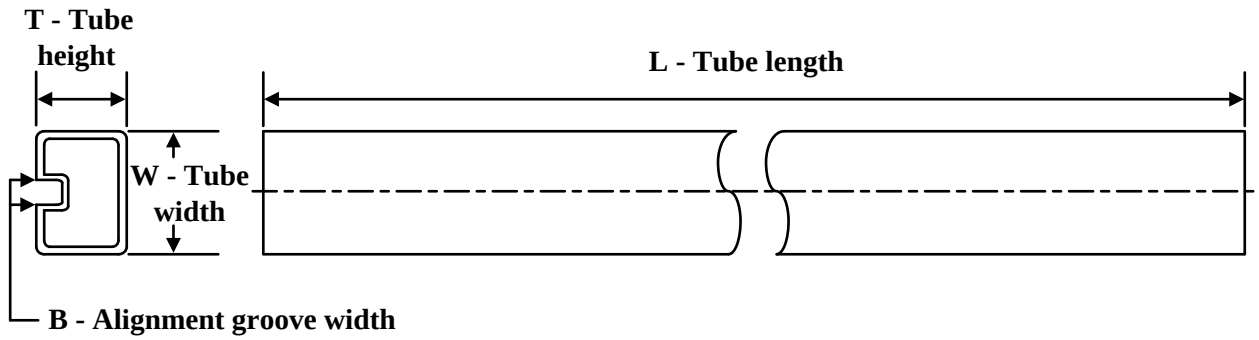
(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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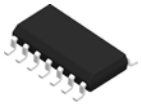
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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74ACT11286D	D	SOIC	14	50	506.6	8	3940	4.32
74ACT11286D.A	D	SOIC	14	50	506.6	8	3940	4.32

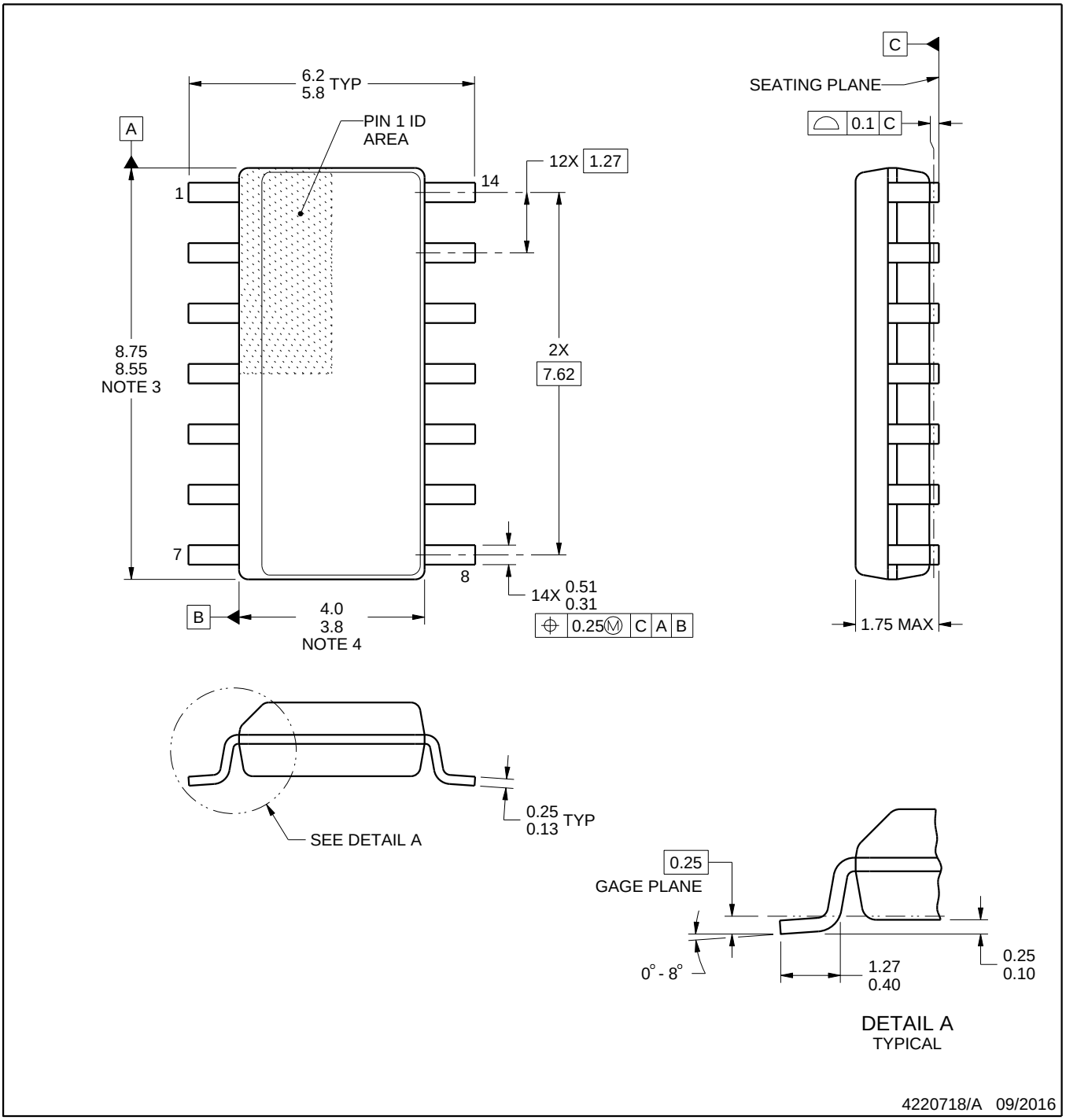


PACKAGE OUTLINE

D0014A

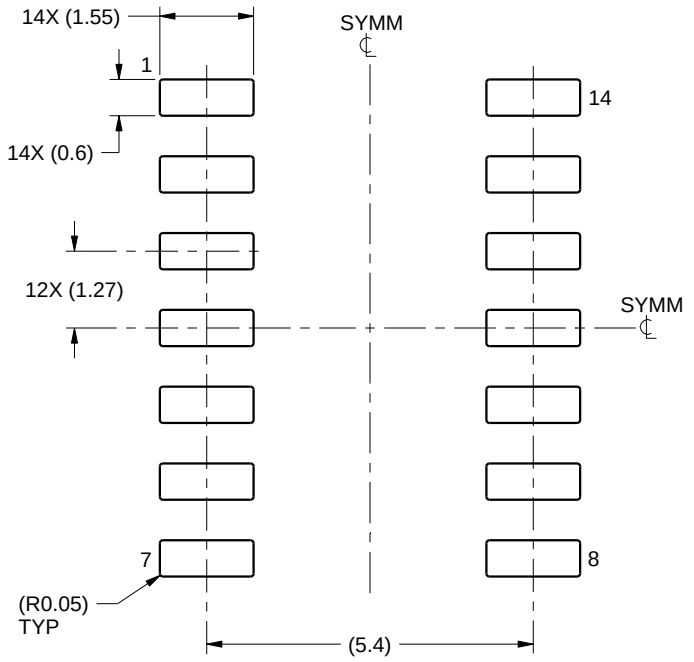
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

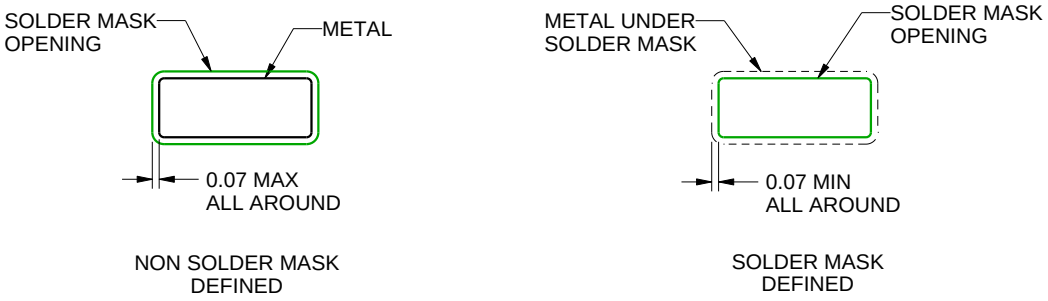


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

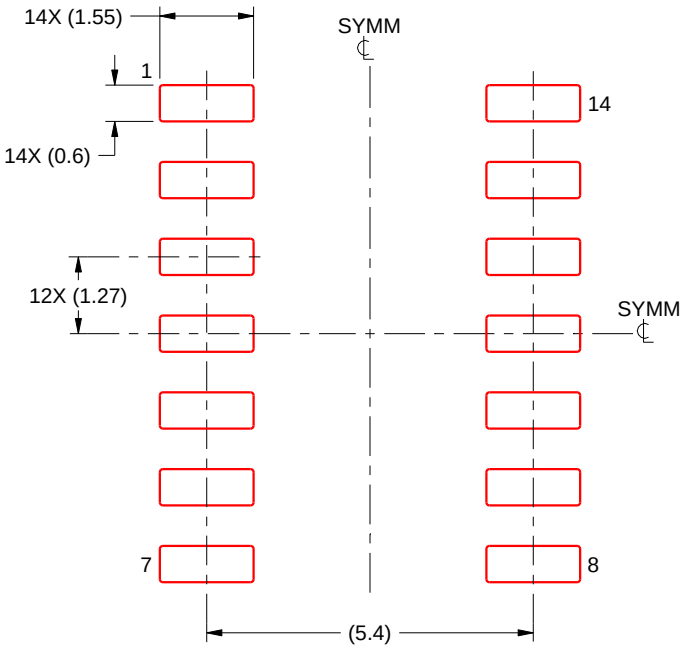
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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